Notice of References Cited

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Examiner

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Reexamination
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Art Unit
Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	Α	US-5,998,860	12-1999	Chan et al.	257/679
*	В	US-6,215,180	04-2001	Chen et al.	257/720
*	С	US-5,661,086	08-1997	Nakashima et al.	257/668
*	D	US-6,255,140	07-2001	Wang, Hsing-Seng	438/122
*	Е	US-6,214,641	04-2001	Akram, Salman	438/107
*	F	US-5,817,535	10-1998	Akram, Salman	438/15
	G	US-			1 400/10
	Н	US-			
	_	US-			
	J	US-			
	к	US-			
	L	US-			
	М	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	0					
	Р					
	Q					
	R					
	s					
	Т					

NON-PATENT DOCUMENTS

		NOT FAILT DOCUMENTS				
*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)				
*	υ	Tummala et al., Microelectronics Packaging Handbook, Semiconductor Packaging – Part II, 2nd Edition, 1997, Chapman & Hall, pages 898-901				
*	٧	Tummala et al., Microelectronics Packaging Handbook, Subsystem Packaging – Part III, 2nd Edition, 1997, Chapman & Hall, pages 223-234				
	w					
	х					

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)

Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

U.S. Patent and Trademark Office PTO-892 (Rev. 01-2001)

Notice of References Cited

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